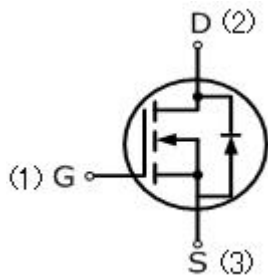


6N90F

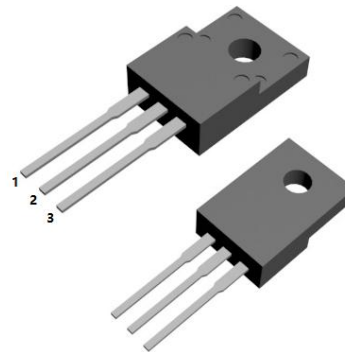
6 Amps,900 Volts N-CHANNEL Power MOSFET

FEATURE

- 6A,900V, $R_{DS(ON)MAX}=2.2\ \Omega$ @ $V_{GS}=10V/3A$
- Low gate charge
- Low C_{iss}
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- RoHS 2.0 Compliant



TO-220F-3L



Absolute Maximum Ratings ($T_C=25^\circ\text{C}$, unless otherwise noted)

| Parameter | Symbol | 6N90F | UNIT |
|---|----------------|-----------|------------------|
| Drain-Source Voltage | V_{DSS} | 900 | V |
| Gate-Source Voltage | V_{GSS} | ± 30 | |
| Continuous Drain Current | I_D | 6 | A |
| Pulsed Drain Current(Note1) | I_{DM} | 24 | |
| Single Pulse Avalanche Energy (Note 2) | E_{AS} | 500 | mJ |
| Reverse Diode dV/dt (Note 3) | dv/dt | 5 | V/ns |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55to+150 | $^\circ\text{C}$ |
| Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | T_L | 260 | $^\circ\text{C}$ |

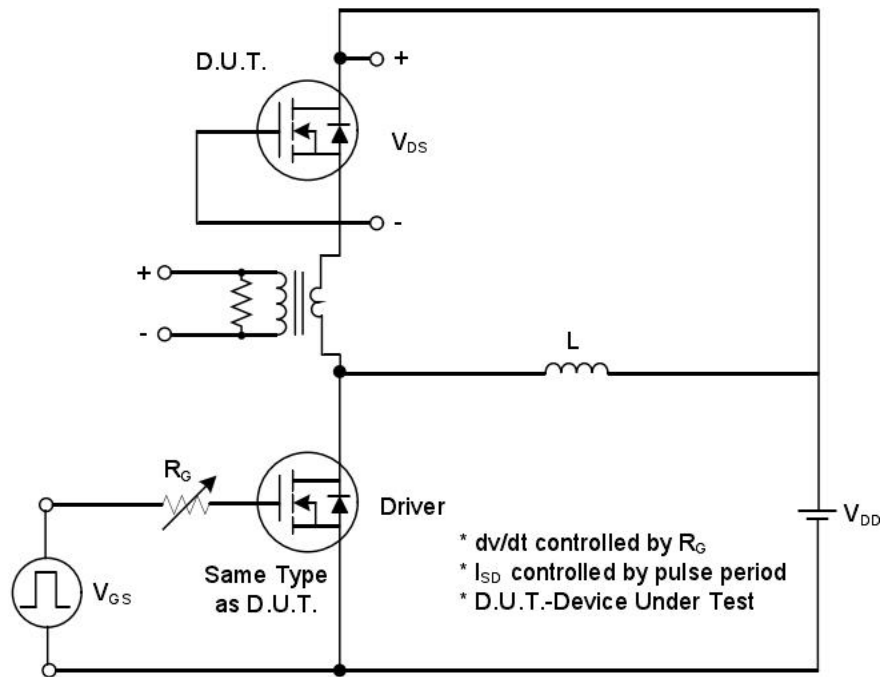
| Parameter | Symbol | 6N90F | Units |
|--------------------------------------|---------------------------------|-------|---------------------------|
| Thermal resistance , Channel to Case | $R_{th(ch-c)}$ | 2.78 | $^\circ\text{C}/\text{W}$ |
| Maximum Power Dissipation | $T_C=25^\circ\text{C}$ P_D | 45 | W |

| Electrical Characteristics ($T_c=25^\circ\text{C}$, unless otherwise noted) | | | | | | |
|---|--------------|--|-----|------|------|----------|
| Parameter | Symbol | Test Conditions | Min | Typ | Max | Units |
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 900 | — | — | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=900V, V_{GS}=0V$ | — | — | 1 | μA |
| Gate-Body Leakage Current, Forward | I_{GSSF} | $V_{GS}=30V, V_{DS}=0V$ | — | — | 100 | nA |
| Gate-Body Leakage Current, Reverse | I_{GSSR} | $V_{GS}=-30V, V_{DS}=0V$ | — | — | -100 | nA |
| On Characteristics | | | | | | |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2 | — | 4 | V |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS}=10V, I_D=3A$ | — | 1.8 | 2.2 | Ω |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS}=25V, V_{GS}=0V,$ $f=1.0\text{MHz}$ | — | 1460 | — | pF |
| Output Capacitance | C_{oss} | | — | 130 | — | pF |
| Reverse Transfer Capacitance | C_{rss} | | — | 23 | — | pF |
| Switching Characteristics | | | | | | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD}=450V, I_D=6A,$ $R_G=9.1\Omega$ | — | 22 | — | ns |
| Turn-On Rise Time | t_r | | — | 45 | — | ns |
| Turn-Off Delay Time | $t_{d(off)}$ | | — | 33 | — | ns |
| Turn-Off Fall Time | t_f | | — | 37 | — | ns |
| Total Gate Charge | Q_g | $V_{DS}=450V, I_D=6A,$ $V_{GS}=10V$ | — | 37 | — | nC |
| Gate-Source Charge | Q_{gs} | | — | 8 | — | nC |
| Gate-Drain Charge | Q_{gd} | | — | 14 | — | nC |
| Drain-Source Body Diode Characteristics and Maximum Ratings | | | | | | |
| Continuous Diode Forward Current | I_S | | — | — | 6 | A |
| Pulsed Diode Forward Current | I_{SM} | | — | — | 24 | A |
| Diode Forward Voltage | V_{SD} | $I_S=6A, V_{GS}=0V$ | — | — | 1.2 | V |
| Reverse Recovery Time | t_{rr} | $V_{GS}=0V, I_S=6A,$ $dI_F/dt=100A/\mu s, (\text{Note}3)$ | — | 390 | — | ns |
| Reverse Recovery Charge | Q_{rr} | | — | 1.4 | — | μC |

Notes

1. Repetitive Rating: pulse width limited by maximum junction temperature.
2. $V_{DD}=50V, L=10\text{mH}, R_g=25\Omega$, starting $T_j=25^\circ\text{C}$.
3. Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.

RATING AND CHARACTERISTIC CURVES



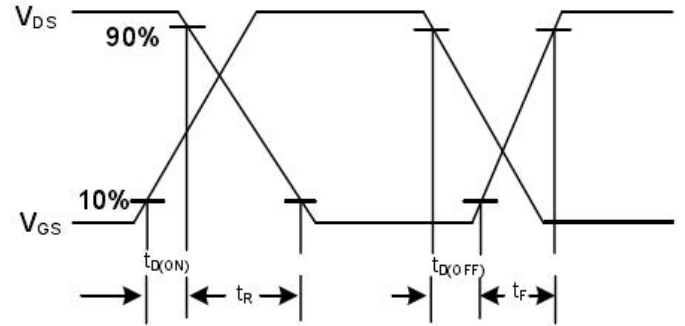
Peak Diode Recovery dv/dt Test Circuit



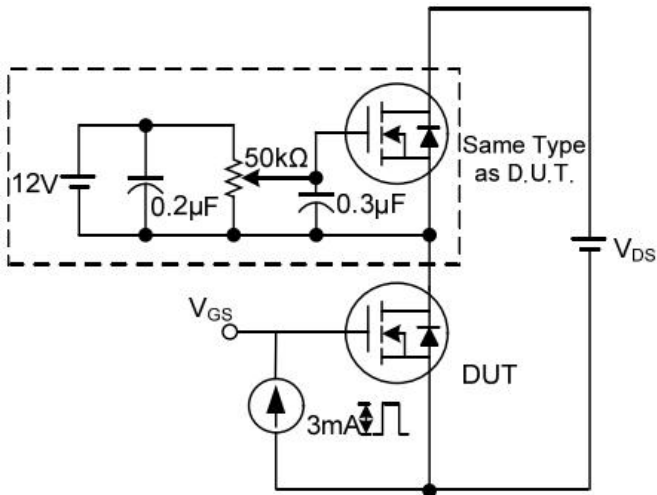
Peak Diode Recovery dv/dt Waveforms



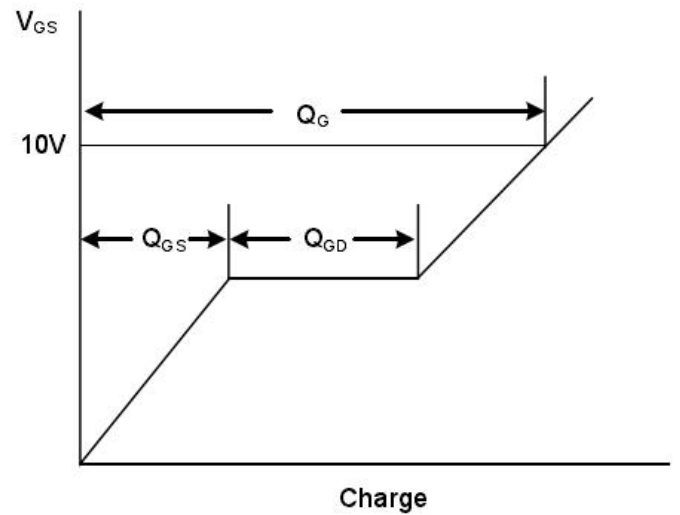
Switching Test Circuit



Switching Waveforms



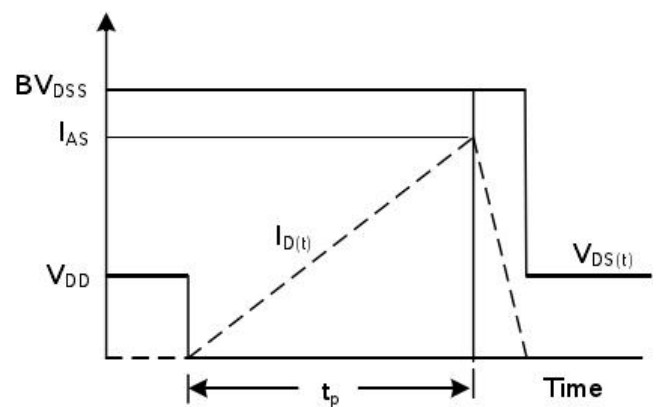
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

RATING AND CHARACTERISTIC CURVES

Figure.1 Typical Output Characteristics

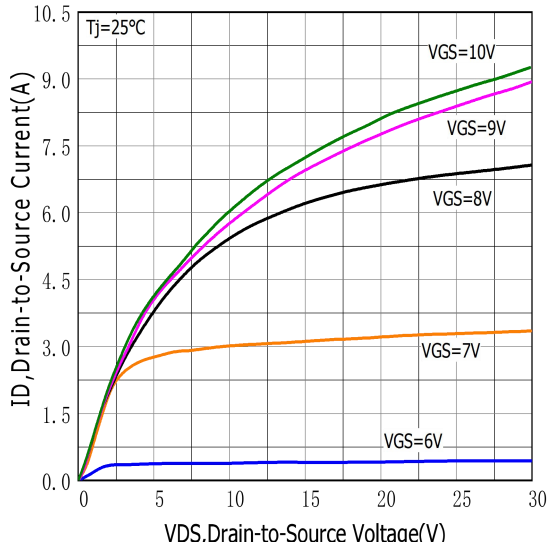


Figure.2 Typical Gate Charge vs Gate to Source Voltage

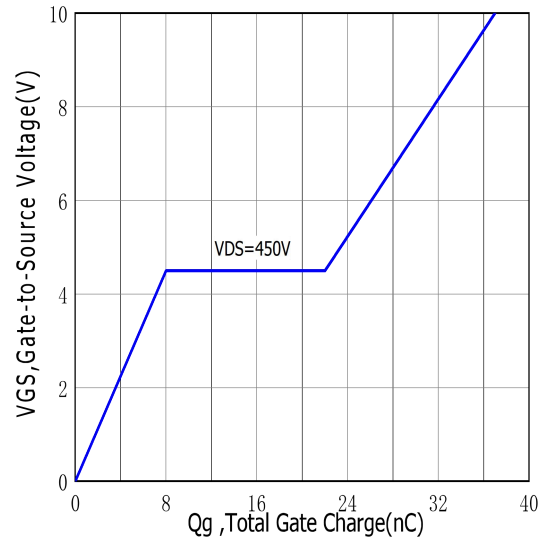


Figure.3 Typical Body Diode Transfer Characteristics

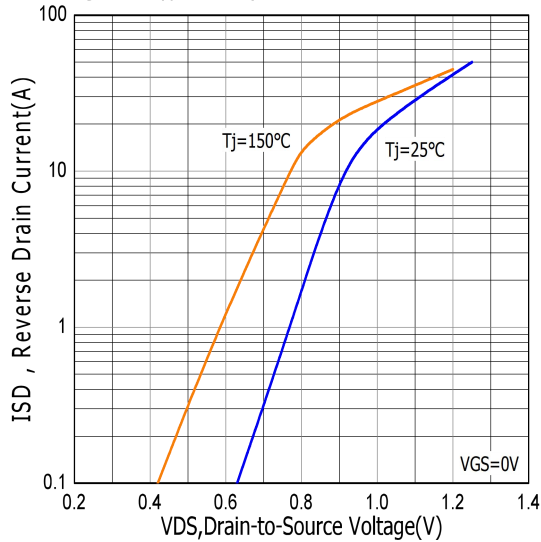


Figure.4 Typical Capacitance vs Drain to Source Voltage

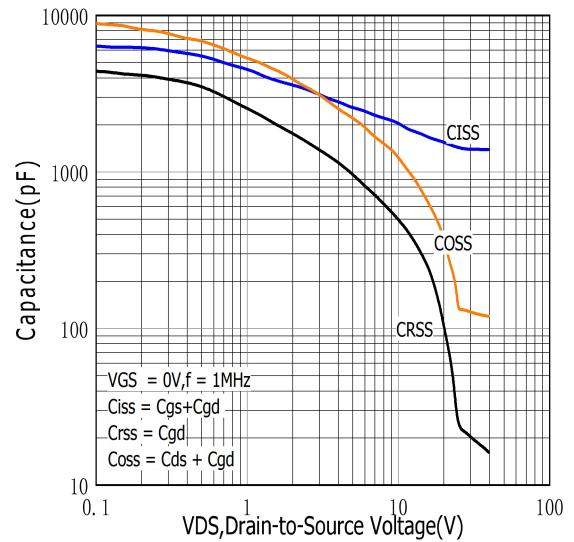


Figure.5 Typical Breakdown Voltage vs Junction Temperature

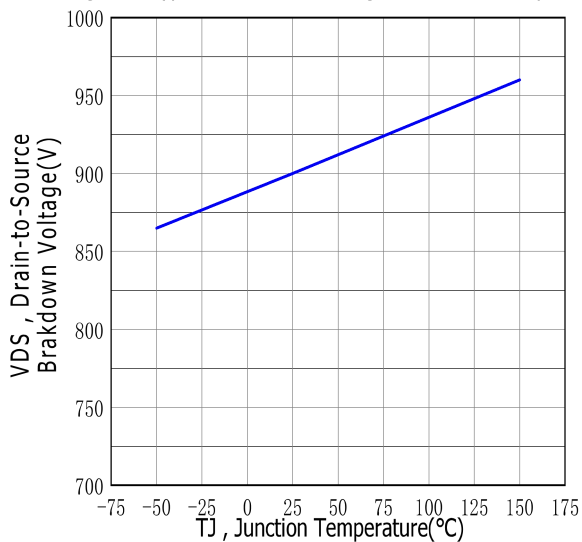


Figure.6 Typical Drain to Source on Resistance vs Junction Temperature

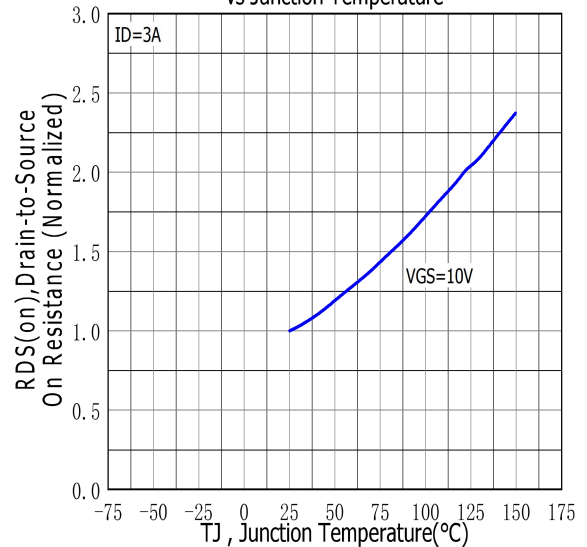


Figure.7 Maximum Forward Bias Safe Operating Area

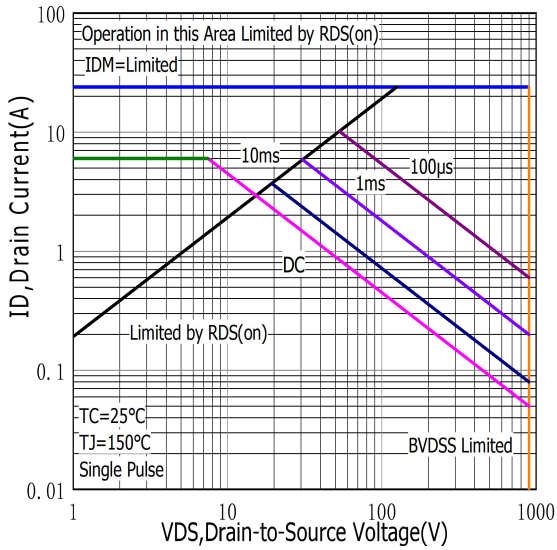


Figure.8 Typical Drain to Source ON Resistance vs Drain Current

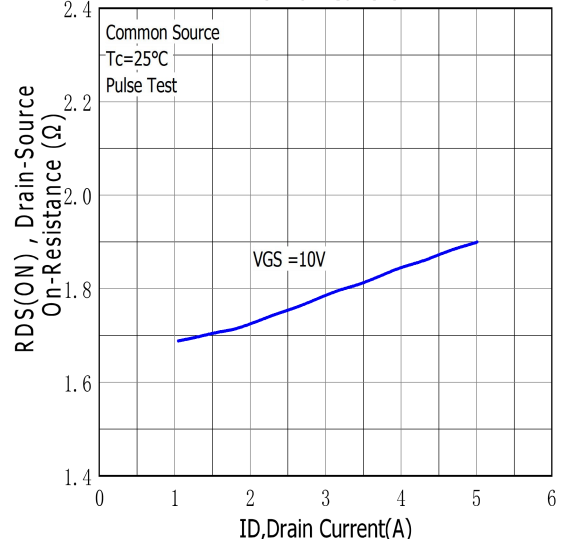


Figure.9 Maximum EAS vs Channel Temperature

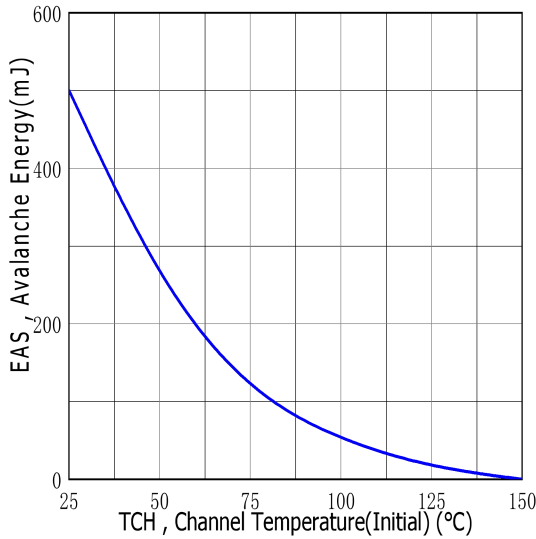


Figure.10 Typical Threshold Voltage vs Case Temperature

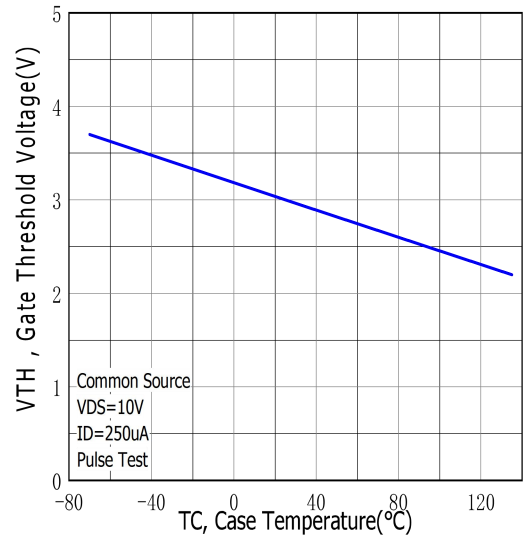


Figure.11 Maximum Effective Thermal Impedance, Junction to Case

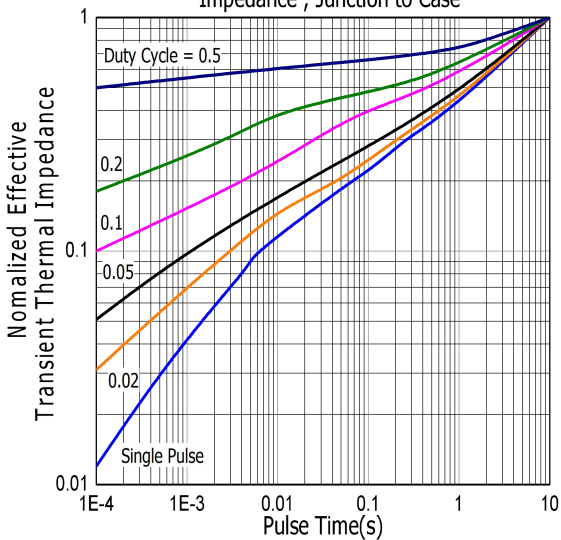
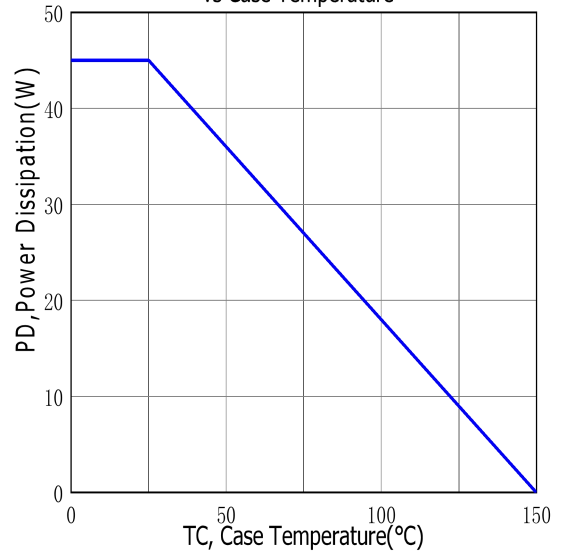
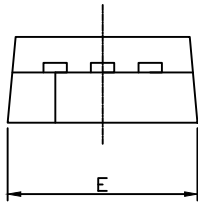
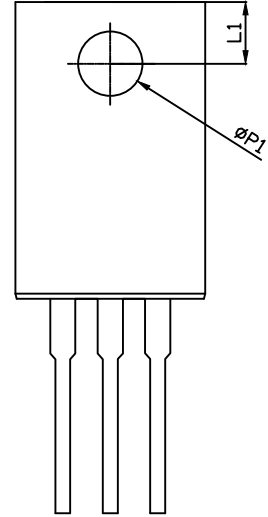
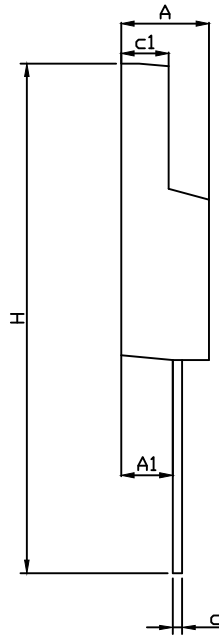
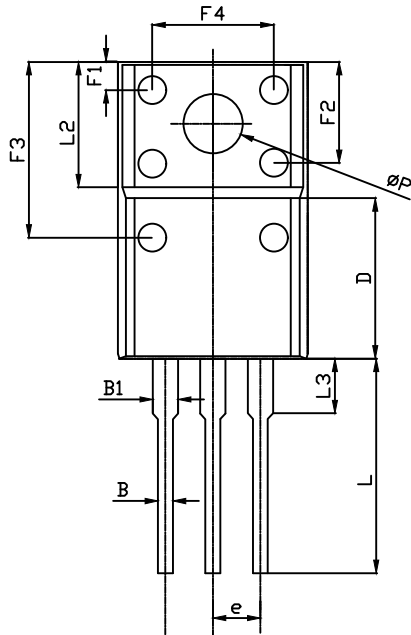


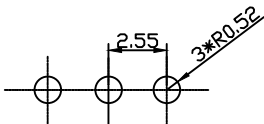
Figure.12 Maximum Power Dissipation vs Case Temperature



TO-220F-3L PACKAGE OUTLINE



RECOMMENDED LAND PATTERN



UNIT: mm

| | MIN | NOM | MAX |
|-----------|-------|---------|-------|
| A | 4.40 | 4.60 | 4.80 |
| A1 | 2.63 | 2.76 | 2.89 |
| B | 0.75 | 0.80 | 0.90 |
| B1 | 1.12 | 1.27 | 1.42 |
| c | 0.40 | 0.50 | 0.60 |
| c1 | 2.60 | 2.70 | 2.80 |
| D | 7.50 | 7.80 | 8.10 |
| e | - | 2.55REF | - |
| E | 9.86 | 10.00 | 10.10 |
| F1 | 1.90 | 2.12 | 2.40 |
| F2 | 5.00 | 5.30 | 5.65 |
| F3 | 8.70 | 9.00 | 9.30 |
| F4 | 6.20 | 6.50 | 6.80 |
| H | 27.80 | 28.30 | 28.80 |
| L | 13.10 | 13.30 | 13.50 |
| L1 | 2.85 | 3.00 | 3.15 |
| L2 | - | 6.70REF | - |
| L3 | 3.10 | 3.60 | 4.10 |
| ΦP | 3.00 | 3.30 | 3.60 |
| ΦP1 | 2.80 | 3.10 | 3.40 |